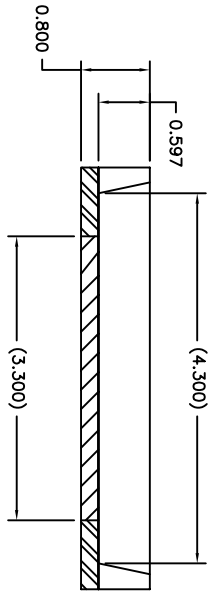
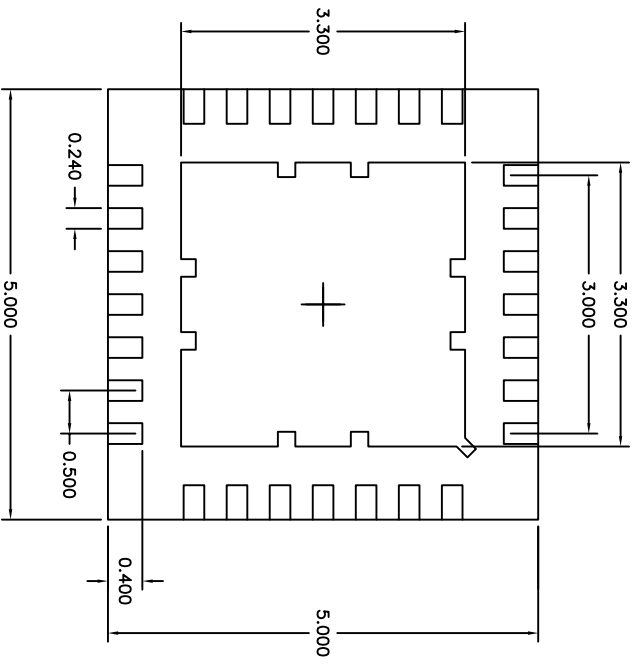
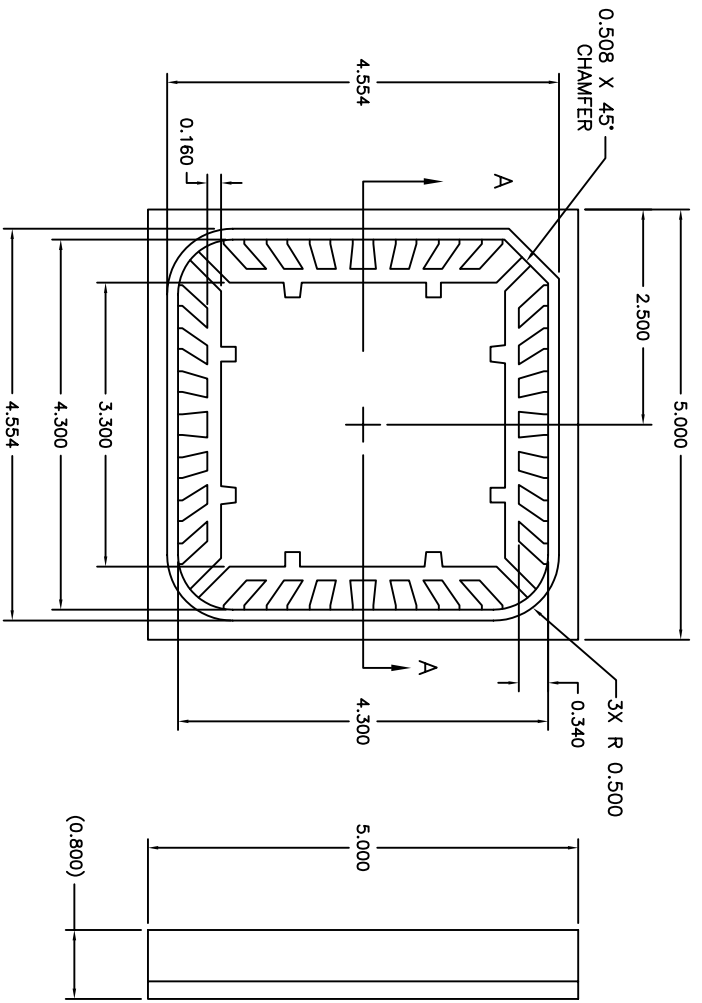


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REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	
10976	04/06/09	PRODUCTION RELEASE	D.BENVANDO



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FRAME: COPPER, 194 FH.
  3. LEAD FINISH: FULL GOLD PLATE.
  4. LEAD FINISH: FULL GOLD PLATE.
  5. FRAME THICKNESS: 0.2030 ± 0.0076.
  6. DIE PAD: 3.300mm X 3.300mm.
  7. JEDEC OUTLINE: MO-220 (VGGD-5)



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

TOLERANCES ARE:

XXXX ± 0.015

XXXX ± 0.050

ANGLES: ± 1°

DO NOT SCALE DRAWING

DRWN BY	VSK	DATE	04/06/09
APP BY	P. FLASKERUD	DATE	04/06/09
CUSTOMER			

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**SEMPAC, INC.**  
 Open-Pak™ Technologies  
 www.sempac.com  
 588 E. WEDDELL DRIVE, SUITE 5  
 SUNNYVALE, CALIFORNIA 94089  
 PHONE: (408) 400-9002 FAX: (408) 400-9006

28 Lead 5mm x 5mm  
 MLP Open-Pak

SIZE PART NO. MLP5X5-28-OP-01  
 SCALE NONE CAD FILE MLP5X5-28-OP-01-R2.DWG

SHEET 1 OF 1

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